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Kind regards,

Team Nexperia



PSMN3R9-60XS

N-channel 60 V, 4.0 mΩ standard level MOSFET in TO220F (SOT186A)

12 September 2013 Product data sheet

1. General description

Standard level N-channel MOSFET in TO220F (SOT186A) package qualified to 175 °C. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

2. Features and benefits

- High efficiency due to low switching and conduction losses
- Isolated package
- Suitable for standard level gate drive

3. Applications

- AC-to-DC power supply equipment
- Motor control
- Server power supplies
- Synchronous rectification

4. Quick reference data

Table 1. Quick reference data

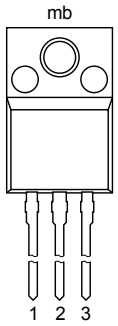
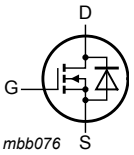
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C		-	-	60	V
I_D	drain current	$T_{mb} = 25$ °C; $V_{GS} = 10$ V; Fig. 1	[1]	-	-	75	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C; Fig. 2		-	-	55	W
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 25$ A; $T_j = 25$ °C; Fig. 12		-	3.25	4	mΩ
Dynamic characteristics							
Q_{GD}	gate-drain charge	$V_{GS} = 10$ V; $I_D = 25$ A; $V_{DS} = 48$ V; Fig. 13; Fig. 14		-	34.7	-	nC
$Q_{G(tot)}$	total gate charge			-	103	-	nC
Avalanche ruggedness							
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10$ V; $T_{j(init)} = 25$ °C; $I_D = 75$ A; $V_{sup} \leq 60$ V; $R_{GS} = 50$ Ω; unclamped; Fig. 3		-	-	478	mJ

Scan or click this QR code to view the latest information for this product

[1] Continuous current is limited by package

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 TO-220F (SOT186A)	
2	D	drain		
3	S	source		
mb		mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN3R9-60XS	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

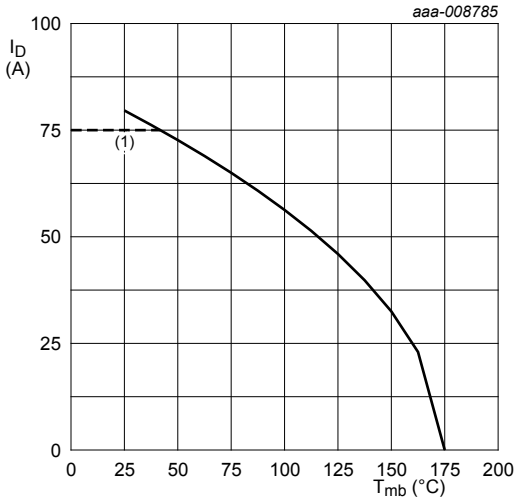
Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C		-	60	V
V_{DGR}	drain-gate voltage	R_{GS} = 20 kΩ		-	60	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	V_{GS} = 10 V; T_{mb} = 100 °C; Fig. 1		-	56	A
		V_{GS} = 10 V; T_{mb} = 25 °C; Fig. 1	[1]	-	75	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10$ µs; T_{mb} = 25 °C; Fig. 4		-	318	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; Fig. 2		-	55	W
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-55	175	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C

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Symbol	Parameter	Conditions		Min	Max	Unit
Source-drain diode						
I_S	source current	T_{mb} = 25 °C		-	46	A
I_{SM}	peak source current	pulsed; $t_p \leq 10$ µs; T_{mb} = 25 °C		-	318	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; I_D = 75 A; $V_{sup} \leq 60$ V; R_{GS} = 50 Ω; unclamped; Fig. 3		-	478	mJ

[1] Continuous current is limited by package



(1) Capped at 75A due to package

Fig. 1. Continuous drain current as a function of mounting base temperature

$V_{GS} \geq 10V$

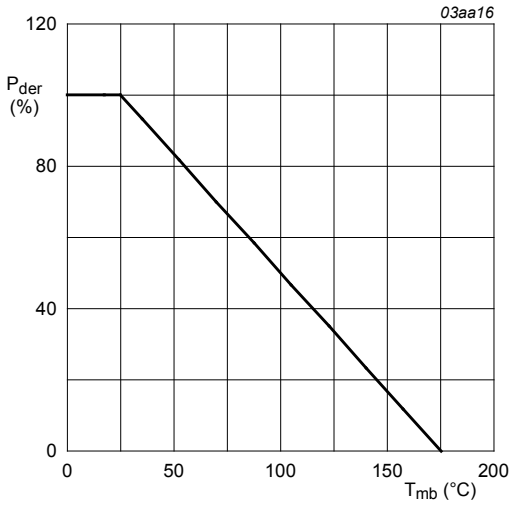


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\ \%$$

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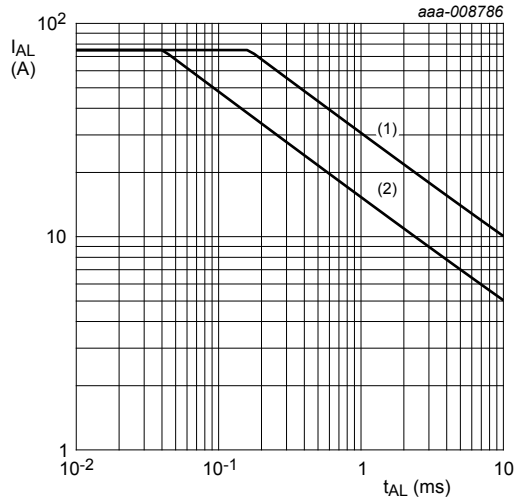


Fig. 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

(1) $T_{j\ (init)} = 25°C$; (2) $T_{j\ (init)} = 100°C$

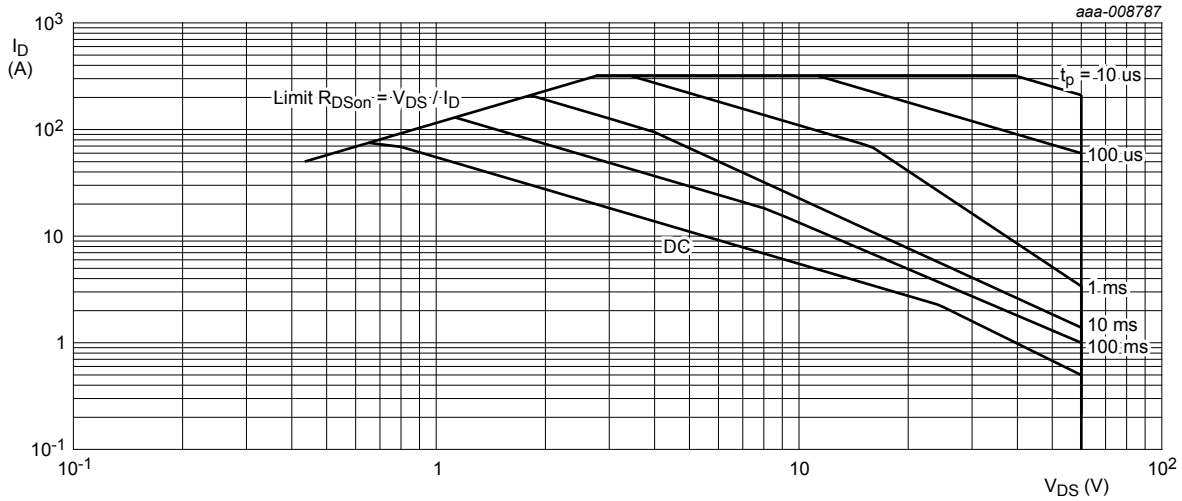


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25°C$; I_{DM} *is a single pulse*

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	Fig. 5		-	2.5	2.73	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	vertical in free air		-	55	-	K/W

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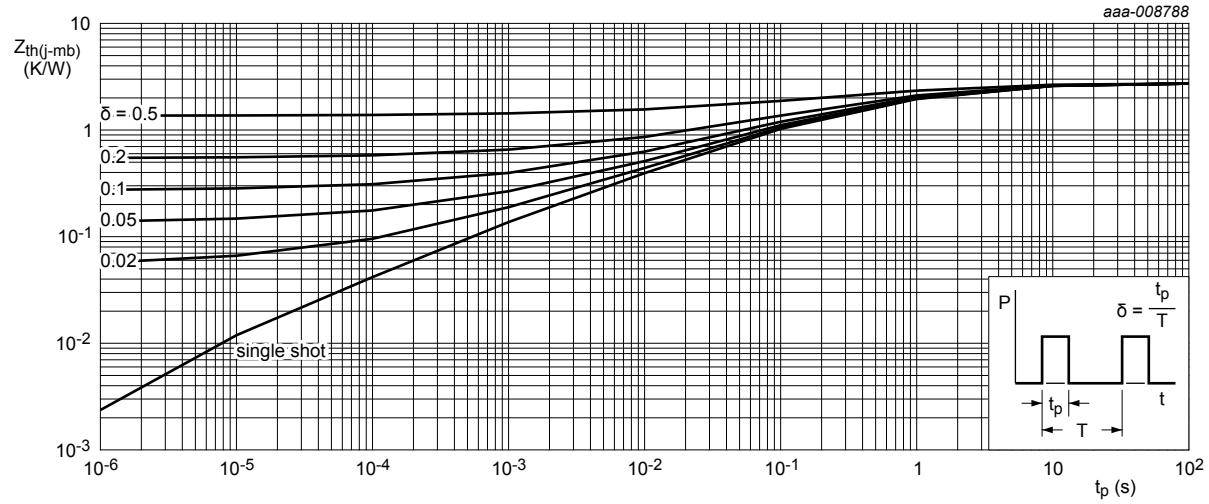


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
C_{isol}	isolation capacitance		[1]	-	10	-	pF
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; sinusoidal waveform; clean and dust free		-	-	2500	V

[1] f = 1 MHz

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 250 µA; V_{GS} = 0 V; T_j = -55 °C		54	-	-	V
		I_D = 250 µA; V_{GS} = 0 V; T_j = 25 °C		60	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; Fig. 9; Fig. 10		2.4	3	4	V
V_{GSth}	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; Fig. 9		-	-	4.5	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 175 °C; Fig. 9		1	-	-	V
I_{DSS}	drain leakage current	V_{DS} = 60 V; V_{GS} = 0 V; T_j = 25 °C		-	0.07	1	µA
		V_{DS} = 60 V; V_{GS} = 0 V; T_j = 175 °C		-	-	500	µA

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Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C		-	2	100	nA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C		-	2	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 175 °C; Fig. 11		-	-	8.7	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; Fig. 12		-	3.25	4	mΩ
R_G	gate resistance	f = 1 MHz		-	0.71	-	Ω
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DS} = 48 V; V_{GS} = 10 V; Fig. 13; Fig. 14		-	103	-	nC
Q_{GS}	gate-source charge			-	25.1	-	nC
Q_{GD}	gate-drain charge			-	34.7	-	nC
C_{iss}	input capacitance	V_{DS} = 25 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25 °C; Fig. 15		-	5494	-	pF
C_{oss}	output capacitance			-	743	-	pF
C_{rss}	reverse transfer capacitance			-	455	-	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 1 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 5 Ω		-	30.6	-	ns
t_r	rise time			-	71.2	-	ns
$t_{d(off)}$	turn-off delay time			-	63.7	-	ns
t_f	fall time			-	64.4	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	I_S = 10 A; V_{GS} = 0 V; T_j = 25 °C; Fig. 16		-	0.76	1.2	V
t_{rr}	reverse recovery time	I_S = 25 A; dI_S/dt = -100 A/µs; V_{GS} = 0 V; V_{DS} = 30 V		-	40.5	-	ns
Q_r	recovered charge			-	53	-	nC

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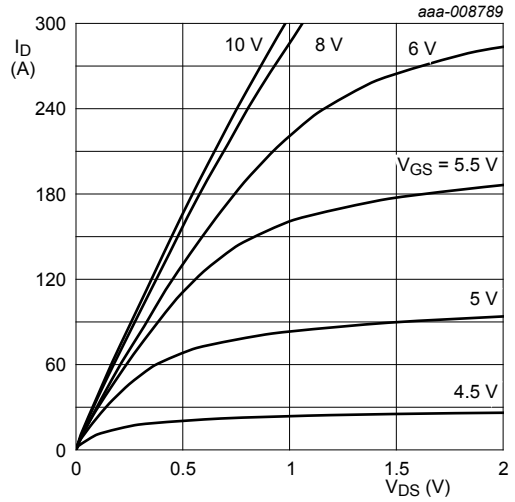


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

$T_j = 25°C$

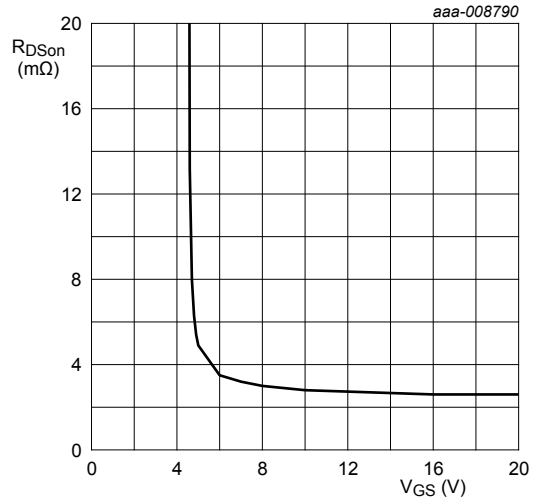


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25°C;\ I_D = 25A$

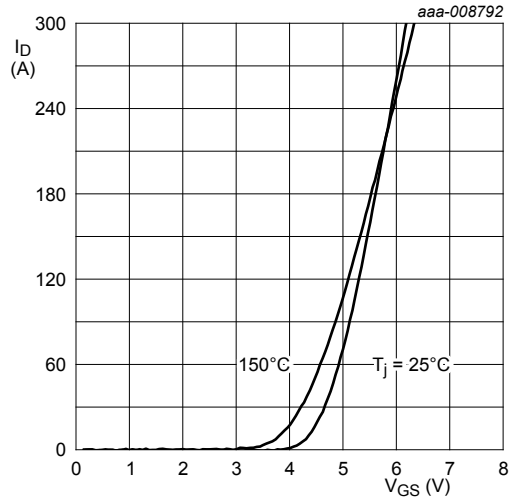


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

$V_{DS} = 10V$

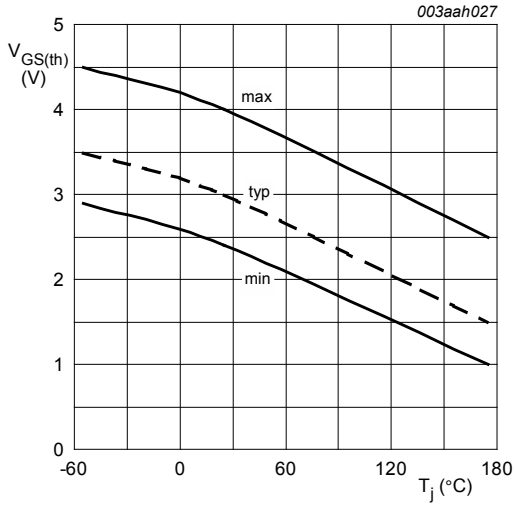


Fig. 9. Gate-source threshold voltage as a function of junction temperature

$I_D = 1\ mA;\ V_{DS} = V_{GS}$

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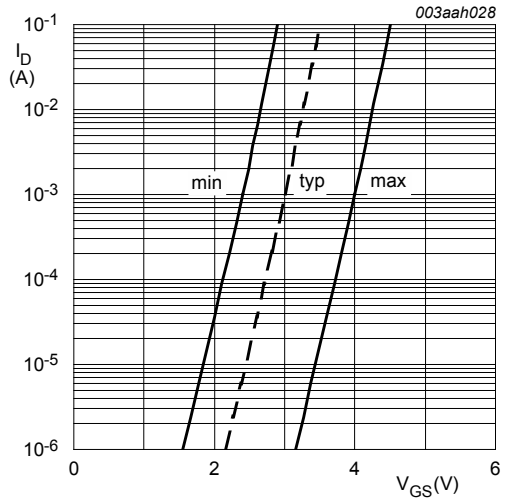


Fig. 10. Sub-threshold drain current as a function of gate-source voltage

$T_j = 25°C;\ V_{DS} = 5V$

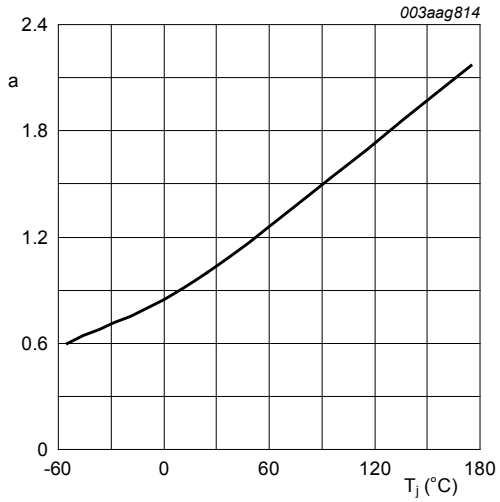


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon(25\,°C)}}$$

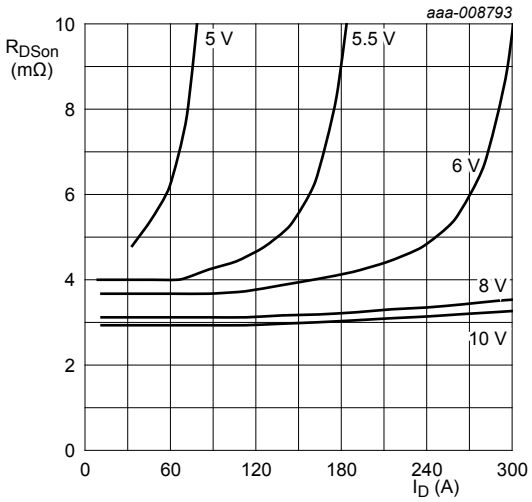


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$T_j = 25°C$

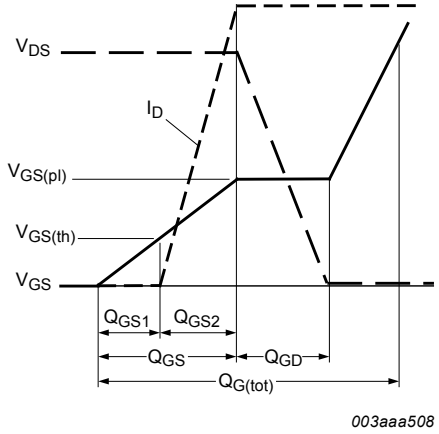


Fig. 13. Gate charge waveform definitions

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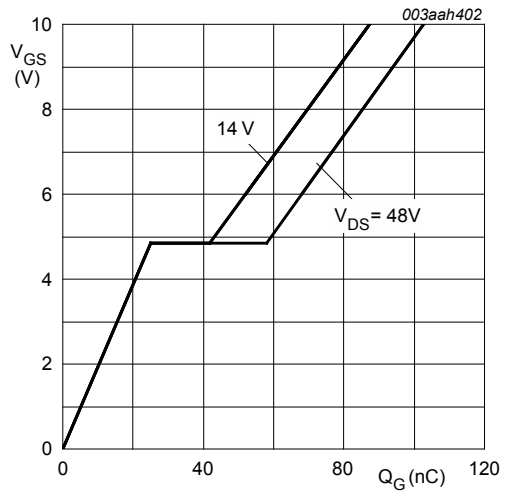


Fig. 14. Gate-source voltage as a function of gate charge; typical values

$T_j = 25°C;\ I_D = 25A$

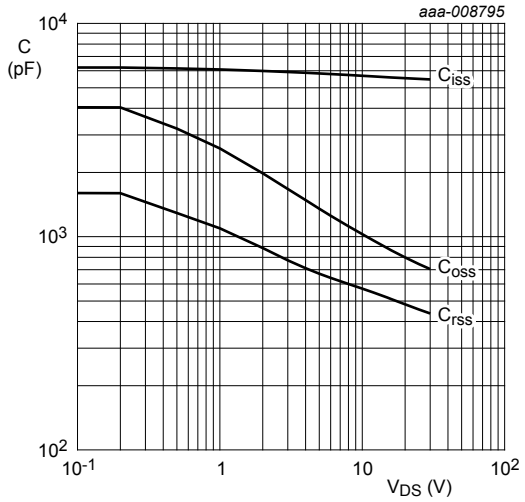


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0V;\ f = 1MHz$

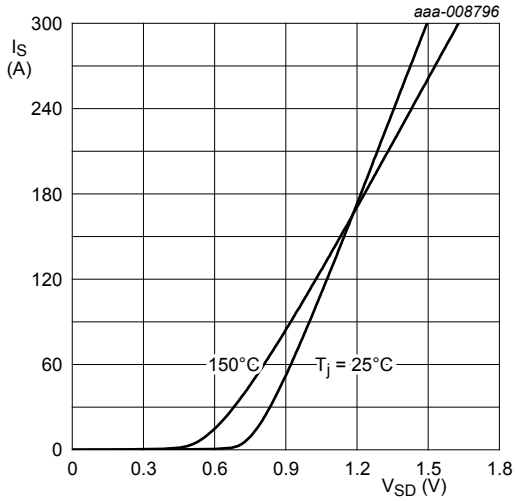


Fig. 16. Source current as a function of source-drain voltage; typical values

$V_{GS} = 0V$

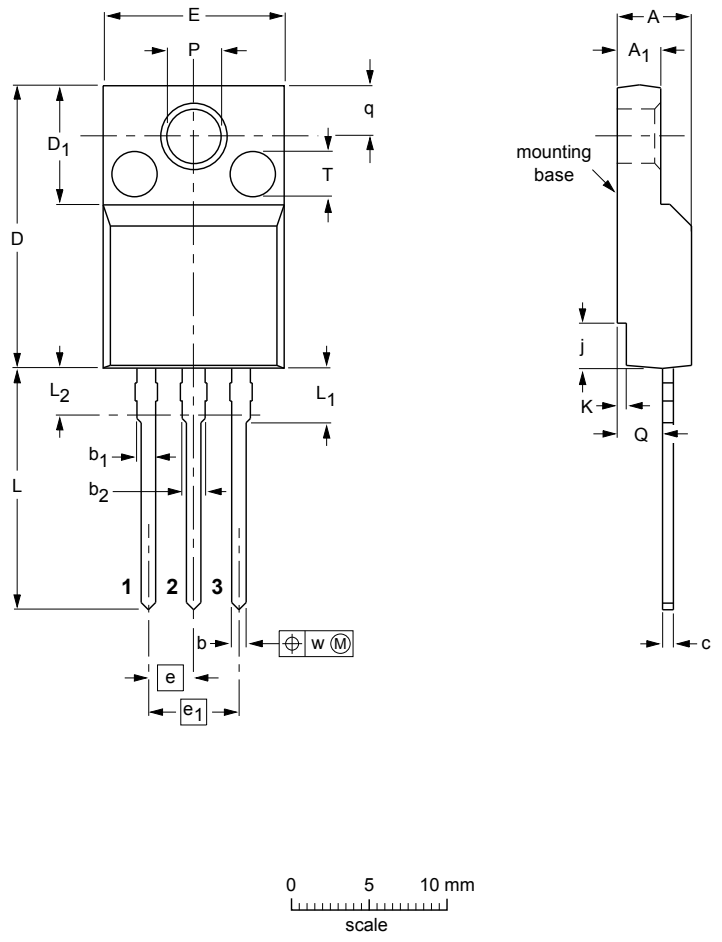
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11. Package outline

Plastic single-ended package; isolated heatsink mounted;
1 mounting hole; 3-lead TO-220 'full pack'

SOT186A



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	b_1	b_2	c	D	D_1	E	e	e_1	j	K	L	L_1	L_2 (1) max.	P	Q	q	T (2)	w
mm	4.6 4.0	2.9 2.5	0.9 0.7	1.1 0.9	1.4 1.0	0.7 0.4	15.8 15.2	6.5 6.3	10.3 9.7	2.54	5.08	2.7 1.7	0.6 0.4	14.4 13.5	3.30 2.79	3	3.2 3.0	2.6 2.3	3.0 2.6	2.5	0.4

Notes

1. Terminal dimensions within this zone are uncontrolled.
2. Both recesses are # 2.5 × 0.8 max. depth

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT186A		3-lead TO-220F				~~02-04-09~~ 06-02-14

Fig. 17. Package outline TO-220F (SOT186A)

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12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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